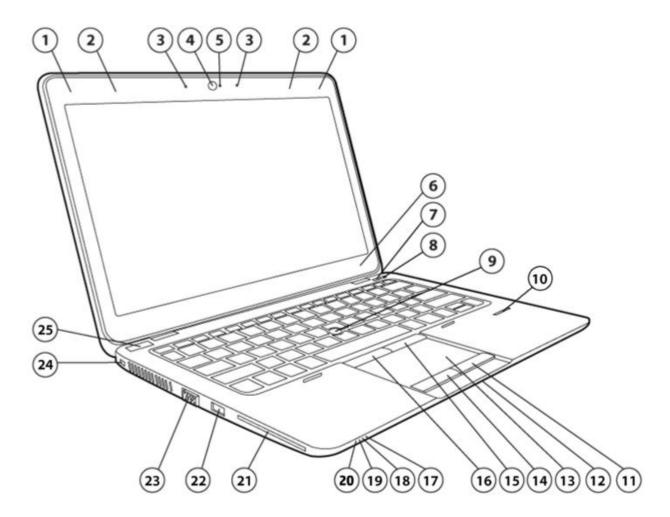
Overview

HP EliteBook 820 G2 Notebook PC



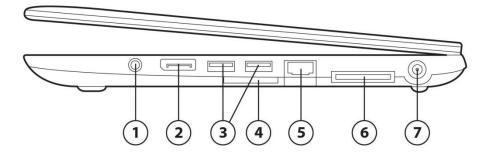
Front/Left

- 1. WLAN antennas (2)
- 2. WWAN antennas (2)
- 3. Internal microphones (2)
- 4. Webcam (select models only)
- 5. Webcam light (select models only)
- 6. Internal display switch
- 7. Wireless button
- 8. Volume mute button
- 9. Pointstick
- 10. Fingerprint reader (optional)
- 11. Right TouchPad button
- 12 NFC sensor (optional)
- 13. TouchPad zone

- 14. Left TouchPad button
- 15. Right pointing stick button
- 16. Left pointing stick button
- 17. Hard drive light
- 18. AC adapter/Battery light
- 19. Power light
- 20. Wireless light
- 21. Smart card reader
- 22. USB 3.0 port
- 23. External VGA monitor port
- 24. Security cable slot
- 25. Power button



Overview



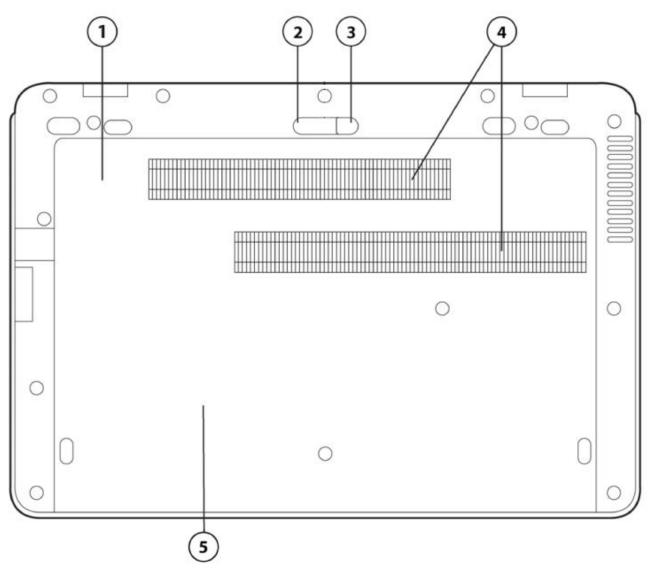
Right

- 1. Audio-out (headphone) jack/Audio-in(microphone) jack
- 2. DisplayPort
- 3. USB 3.0 ports (2)
- 4. Memory card reader

- 5. Drop-jaw Ethernet port (RJ-45)
- 6. Docking port
- 7. Power connector



Overview



Bottom

- 1. EasyAccess panel
- 2. EasyAccess panel release latch
- 3. Security screw

- 4. Vents (2)
- 5. SIM slot (inside the panel)*



Overview

AT A GLANCE

- Windows 10 versions, Windows 8.1 versions, Windows 7 versions, Ubuntu Linux or FreeDOS 2.0
- Magnesium chassis, HP DuraFinish, HP DisplaySafe frame, HP duraKeys, precision aluminum drop hinge, aluminum palm rest
- 4-step Soft-touch paint process
- Patent-pending Drop-jaw Ethernet port
- EasyAccess door to quickly access most components for easy serviceability
- Full-sized spill-resistant keyboard; optional back-lit keyboard keeps you productive in low-light settings
- Choice of 5th Generation Intel[®] Core[™] i7, i5 and i3 processors
- Memory options up to 16 GB
- Weight starting at 2.94 lbs/1.33 kg
- Storage options up to 1 TB Hard Drives, 512 GB Solid State Drives, or 256GB PCIe Solid State Drive
- M.2 32GB Flash Cache for Intel Smart Response Technology installed in the factory
- M.2 120GB Solid State Drive & 256GB PCIe Solid State Drive can be configured as primary storage or combined with a SATA drive for dual storage performance
- Choice of Touch or Non Touch 12.5" diagonal displays
- Easily hot dock with the UltraSlim Docking Station
- DisplayPort for high resolution support
- Touchpad with scroll zone, on/off button with LED indicator
- Enhanced security features including HP Sure Start self-healing BIOS, HP Client Security and optional HP Fingerprint Reader
- Optional HD webcam with dual-microphone array for video conferencing
- HD Audio with DTS Studio Sound™ optimized for high fidelity audio
- Wireless and speaker mute buttons
- Supports a broad range of wireless LAN and wireless WAN options, including 4G LTE, for connectivity on the go
- UEFI BIOS Compliant with 2.3.1 UEFI Specification

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Features

PRODUCT NAME

HP ELITEBOOK 820 G2 NOTEBOOK PC

OPERATING SYSTEM

Preinstalled	Windows 10 Pro 64* Windows 10 Home 64* Windows 8.1 Pro 64* Windows 8.1 64* Windows 7 Professional 64 (available through downgrade rights from Windows 10 Pro)*** Windows 7 Professional 32 (available through downgrade rights from Windows 10 Pro)*** Windows 7 Professional 64 (available through downgrade rights form Windows 8.1 Pro)** Windows 7 Professional 32 (available through downgrade rights form Windows 8.1 Pro)** Windows 7 Professional 32 (available through downgrade rights form Windows 8.1 Pro)** Windows 7 Professional 32 (available through downgrade rights form Windows 8.1 Pro)** Windows 7 Professional 32 (available through downgrade rights form Windows 8.1 Pro)** Windows 7 Professional 32 (available through downgrade rights form Windows 8.1 Pro)** Windows 7 Professional 32 (available through downgrade rights form Windows 8.1 Pro)** Windows 7 Professional 32 (available through downgrade rights form Windows 8.1 Pro)**
Web only support	Windows 10 Pro 64* Windows 10 Home 64* Windows 10 Enterprise 64* Windows 8.1 64* Windows 8.1 Pro 64* Windows 8.1 Enterprise 64* Windows 7 Professional 64 (available through downgrade rights from Windows 10 Pro)*** Windows 7 Professional 32 (available through downgrade rights from Windows 10 Pro)*** Windows 7 Professional 64 (available through downgrade rights form Windows 8.1 Pro)** Windows 7 Professional 64 (available through downgrade rights form Windows 8.1 Pro)** Windows 7 Professional 64 (available through downgrade rights form Windows 8.1 Pro)** Windows 7 Professional 32 (available through downgrade rights form Windows 8.1 Pro)** Windows 7 Professional 32 (available through downgrade rights form Windows 8.1 Pro)** Windows 7 Professional 32* Windows 7 Enterprise 64* Windows 7 Enterprise 32*

* Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://http://www.microsoft.com

** This system is preinstalled with Windows 7 Professional software and also comes with a license and media for Windows 8 Pro software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

***This system is preinstalled with Windows 7 Professional software and also comes with a license and media for Windows 10 Pro software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.



Features

PROCESSOR

- 5th Generation Intel[®] Core™ i3-5010U 2.1 GHz 3-MB L3 Cache, 15W
- 5th Generation Intel[®] Core[™] i5-5200U 2.2 GHz (max turbo frequency 2.7-GHz), 3 MB L3 cache, 15W
- 5th Generation Intel[®] Core[™] i5-5300U 2.3 GHz (max turbo frequency 2.9-GHz), 3 MB L3 Cache, 15W
- 5th Generation Intel[®] Core™ i7-5500U 2.4 GHz (max turbo frequency 3.0-GHz), 4 MB L3 Cache, 15W
- 5th Generation Intel[®] Core™ i7-5600U 2.6 GHz (max turbo frequency 3.2-GHz), 4 MB L3 Cache, 15W

* Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. 64-bit computing on Intel® architecture requires a computer system with a processor, chipset, BIOS, operating system, device drivers, and applications enabled for Intel® 64 architecture. Processors will not operate (including 32-bit operation) without an Intel® 64 architecture-enabled BIOS. Performance will vary depending on your hardware and software configurations. Intel's numbering is not a measurement of higher performance.

** Not available with Intel iAMT (*Not available with vPro)

NOTE: Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

INTEL TURBO BOOST TECHNOLOGY*

Intel Turbo Boost is a feature that speeds up the CPU for a short time. It is similar to overclocking the processor, except within a framework provided by Intel. This feature provides additional performance and allows the computer to perform certain tasks more quickly. It also draws additional power and generates additional heat. Therefore, if Turbo Boost is used while powered from battery, it causes additional stress on the battery.

Using Turbo Boost while powered from battery might impact battery cycle life. Cycle life describes how long the battery will last before it needs to be replaced. A cycle refers to one complete charge/discharge cycle of the battery. Because Turbo Boost causes extra stress on the battery, it often shortens the lifetime of the battery.

HP decided not to enable Turbo Boost when powered from battery. This decision was based on the desire to give customers the greatest battery cycle life possible. Turbo Boost is enabled when powered from AC adapter.

Based on customer requests, HP will provide an option to enable Turbo Boost while powered from battery. For the 2013 platform, it will be an F10 option. Turbo Boost will be available for devices powered from battery by the end of the year. The additional performance might cause a slight reduction in battery cycle life, but will not void the battery warranty.

*Implementing Turbo Boost in F10 option is only allowed for batteries over 40WHr. Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.

CHIPSET

Chipset integrated with processor

INTEL CORE 15 WITH VPRO/CORE 17 WITH VPRO TECHNOLOGY CAPABLE

Intel Core i5 with vPro and Core i7 with vPro technology is a selectable feature that is available on units configured with select processors, an Intel Centrino[®] Advanced-N or Ultimate-N WLAN module and a preinstalled Windows operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel Active Management Technology 9.0 (iAMT) offers built-in manageability and proactive security for networked notebook PCs, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the



Features

network, isolate infected systems, and update PCs regardless of their power state. *Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

NOTE: Some functionality of this technology, such as Intel[®] Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependent on 3rd party software providers. Microsoft Windows required.

GRAPHICS

Integrated: Intel[®] HD* Graphics 5500

*HD content required to view HD images.

DISPLAY

HP EliteBook 820 G2 Notebook PC Internal

Non Touch

12.5" diagonal LED-backlit HD* anti-glare SVA flat (1366x768)

12.5" diagonal LED-backlit HD* anti-glare SVA flat (1366x768) with camera

12.5" diagonal LED-backlit FHD anti-glare UWVA ultra slim (1920 x 1080)

12.5" diagonal LED-backlit FHD anti-glare UWVA ultra slim (1920 x 1080) with camera

*HD content required to view HD images.

Touch

12.5" diagonal LED-backlit FHD UWVA ultra slim (1920 x 1080) with camera Touch panel has chemically-strengthened Corning® Gorilla® Glass 3 top cover

External

Up to 32-bit per pixel color depth

VGA

Port supports resolutions up to 1920 x 1200 external resolution @75 Hz

DisplayPort

Supports resolutions up to 3840 x 2160 @ 60Hz. Supports Multi-Stream Transport (MST) where three displays can be daisy chained with digital displays through DisplayPort Only. The full resolution of each display will be limited as you reach 3 displays due to the bandwidth limitations with a maximum resolution of:

- 2560x1600@60Hz for 2 displays
- 1920x1200@60Hz for 3 displays

Number of Displays supported

3 With Optional* UltraSlim Docking Station - *Sold separately.

STORAGE AND DRIVES

Primary Storage Bay



Features

Hard Drives*

320 GB 7200rpm SATA Hard Drive 500 GB 7200rpm SATA Hard Drive 500 GB 7200rpm Self-Encrypting Drive 500 GB 5400 rpm Self Encrypting Drive (FIPS-140-2) 500 GB 5400rpm + 8GB NAND SATA Hybrid Hard Drive 1TB 5400rpm SATA Hard Drive

Solid State Drive*

120 GB M.2 Solid State Drive 128 GB SATA-3 MLC Solid State Drive 128 GB SATA-3 TLC Solid State Drive 180 GB SATA-3 MLC Solid State Drive 180 GB SATA-3 MLC Solid State Drive 240 GB SATA-3 MLC Solid State Drive 256 GB SATA-3 TLC Solid State Drive 256 GB M.2 PCIe Solid State Drive 512 GB SATA-3 TLC Solid State Drive 512 GB SATA-3 TLC Solid State Drive

HP 3D DriveGuard (Windows only)

HP 3D DriveGuard mitigates the risk of hard drive failures, safeguarding your data when you are on the go by sensing sudden movement and protecting the hard drive. The hard drive is mounted directly to the notebook frame, reducing the transmission of shock to the hard drive.

*For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 16 GB (for Windows 7) and up to 30 GB (for Windows 8 and 10) of system disk is reserved for the system recovery software.

FLASH CACHE

32 GB M.2 (NGFF) Optional 32 GB M.2 flash cache module support for Intel Smart Response Technology. Available only with standard non-SED hard drive.)

MEMORY

Standard

DDR3L-1600 (Transfer rates up to 1600 MT/s) Two SODIMM slots supporting dual-channel memory

4 GB Total System Memory (4 GB x 1) 8 GB Total System Memory (4 GB x 2) 8 GB Total System Memory (8 GB x 1) 16 GB Total System Memory (8 GB x 2)

Maximum Upgradeable to 16 GB with optional 8 GB SODIMMs in slots 1 and 2* Dual-channel



Features

Maximized dual-channel performance requires SODIMMs of the same size and speed in both memory slots.

* Maximum memory capacities assume Windows 64-bit operating systems or Linux. With Windows 32-bit operating systems, memory above 3 GB may not all be available due to system resource requirements. NOTE: Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to

NOTE: Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

Wireless

Support for a broad range of secure, integrated wireless LAN and wireless WAN options featuring support for the latest industry standards. Broadband Wireless (WWAN) requires a Windows operating system and is available in select countries as a standard, factory configurable feature only. Integrated Bluetooth is also available (factory configurable only) and can be combined with any of the supported wireless LAN and wireless WAN options.

Broadband Wireless (WWAN)*

HP lt4112 LTE/HSPA+ Qualcomm[®] Gobi™ 4G Module HP lt4211 LTE/EV-DO/HSPA+ Qualcomm[®] Gobi™ 4G Module** HP hs3110 HSPA+ Mobile Broadband Module

Wireless LAN (WLAN)*

Intel[®] Dual Band Wireless-AC 7265 802.11 ac (2X2) Wi-Fi + Bluetooth[®] Intel[®] Dual Band Wireless-7265AN 802.11 a/b/g/n (2X2) Wi-Fi + Bluetooth[®] Intel[®] Dual Band Wireless-AC 3160 802.11 ac (1x1) Wi-Fi + Bluetooth[®]

*Wireless access point and Internet service is required and is not included. Availability of public wireless access points limited. **4G LTE WWAN is an optional feature, not available on all products, in all regions and requires separately purchased service contract. Check with service provider for coverage and availability. Connection speeds will vary due to location, environment, network conditions, and other factors.

Communications

Intel® I218LM Gigabit* Network Connection (10/100/1000 NIC)

* The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

Optional Near Field Communication (NFC)

AUDIO/MULTIMEDIA

Audio

HD Audio with DTS Studio Sound[™] 2 Integrated stereo speakers Integrated dual-microphone array; located in the display Function keys for microphone mute, volume up, volume down Stereo headphone/line out Stereo microphone/line in

Webcam Optional* 720p HD** webcam



HP EliteBook 820 G2 Notebook PC

QuickSpecs

Features

- HD format (widescreen) •
- Supports videoconferencing (non-HD) and still image capture •
- High quality fixed focus lens
- Video capture at various resolutions up to 1280x720 resolution (720p) and up to 30fps •
- M-JPEG compression supports higher frame rates for video capture and videoconferencing ٠
- Improved low light sensitivity •
- Improved dynamic range
- Skype-ready ***

* Sold separately.

** HD content required to view HD images.

***Internet access required.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Kevboard

The HP spill-resistant keyboard is designed using a thin layer of Mylar film under the keyboard and includes an all-metal keyboard deck for greater rigidity, as well as HP DuraKeys. The 101/102-key compatible keyboard features a full-pitch key layout with desktop keyboard features, such as editing keys, both left and right control and alt keys, and function keys. US and International key layouts are available. Backlit keyboard available as an option.

Pointing Devices

Touchpad with scroll zone, on/off button with LED indicator, two-way scroll, two pick buttons

Buttons and Function Keys

Separate discrete buttons provide easy access to WLAN on/off and speaker mute. Function keys provide control of features including: standby mode, display brightness, external display, microphone mute, volume down, and volume up.

SOFTWARE AND SECURITY

Preinstalled Software with Windows Operating System

BIOS

HP BIOSphere¹ **HP** Sure Start HP DriveLock | HP Automatic Drive Lock HP BIOS Protection² HP Disk Sanitizer ³ HP SpareKev⁴ **BIOS Update via Network** Master Boot Record Security **Power On Authentication** Pre-Boot Security Secure Erase ⁵ **Hybrid Boot** Measured Boot Secure Boot Absolute Persistence Module ⁶

1. Available only on business PCs with HP BIOS.

May require a manual recovery step if all copies of BIOS are compromised or deleted. BIOS adheres to NIST SP800-147



Features

- 3. For the use cases outlined in the DOD 5220.22-M Supplement.Does not support solid state drives.
- 4. Requires initial user set up.
- 5. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88.

6. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

MultiMedia

CyberLink PowerDVD CyberLink YouCam BE

Communication

HP Connection Manager with support for HP Mobile Connect (Windows 7 only)² HP GPS and Location¹ HP Mobile Connect (Windows 8 only)² HP Wireless Hotspot³ (Windows 8 only) Intel WiDi Software⁴ HP Roaming Alert Intel My WiFi and Wireless Drivers

HP Value Add Software

Getting Started with Windows 8 HP 3D DriveGuard (Windows required) HP ePrint Driver (HP Exclusive)⁵ HP Hotkey Support HP PageLift HP Recovery Manager (Windows 7 only) HP Support Assistant HP Recovery Disc Creator (Windows 7 only) UEFI System Diagnostics W8

3rd Party

Adobe® Flash Player (Commercial) Foxit PhantomPDF Express for HP Bing Search Skype⁶ Buy Office

NOTE: HP Recovery Manager enables fast recovery of the factory preinstalled image if the system becomes corrupted or if important system files are accidentally deleted. Up to 16 GB (for Windows 7) and 36 GB (for Windows 8) of system disk is reserved for the system recovery software.

1. GPS access requires an unobstructed path to multiple satellites. Performance may be affected if/when used inside of buildings, bridges or heavily congested metropolitan areas. Requires separately purchased GPS navigation software available from multiple GPS applications.

2. HP Mobile Connect is only available on selective devices with wwan. For geographical availability refer to http://www.hp.com/go/mobileconnect

3. The wireless hotspot application requires an active internet connection that is shared with the connecting devices.



Features

Wireless hotspot data usage may incur additional charges. Check with your service provider for plan details.
Integrated Intel Wi-Di feature is available on select configurations only and requires separately purchased projector, tv or computer monitor with an integrated or external Wi-Di receiver. External Wi-Di receivers connect to the projector, tv or computer monitor via a standard HDMI cable, also sold separately.
Requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see http://www.hp.com/go/businessmobileprinting.

6. Skype is not offered in China.

Manageability

HP Driver Packs ¹ HP SoftPaq Download Manager (SDM) HP System Software Manager (SSM)¹ HP BIOS Config Utility (BCU) ¹ HP Client Catalog / HP CIK for Microsoft SCCM¹ LANDESK Management ¹

1. Not preinstalled For more information on HP Client Management Solutions refer to: http://www.hp.com/go/clientmanagement.

Standard Security Features

HP Client Security Manager (Windows only) HP Device Access Manager HP Drive Encryption¹ HP File Sanitizer² Microsoft Security Essentials (Windows 7 only)³

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

Security Hardware

TPM Embedded Security Chip 1.2 Security lock slot Fingerprint Reader Integrated Smart Card Reader

1. Requires Windows. Data is protected prior to Drive Encryption login. Turning the PC off or into hibernate logs out of Drive Encryption and prevents data access.

2. For the use cases outlined in the DOD 5220.22-M Supplement. Supports standard Hard Drives. Initial setup required.

3. Opt in and internet connection required for updates.

POWER

Power Supply

HP 45W Smart AC Adapter 45W 2-prong 7.4mm DC jack AC Adapter (Only for Japan) HP 65W Smart EM AC Adapter (China and India only)

Power cord is configurable; either 3.2 feet or 6 feet (1.0 or 1.8 meter) Total length including external AC adapter is 9.2 feet or 12 feet (2.86 or 3.66 meter).



Features

Primary Battery

3-cell HP Long Life Polymer 26 WHr 3-cell HP Long Life Polymer 46 WHr

Battery Life*

Hardware details	Battery	UMA Graphics
HDD	3-cell (46 WHr)	Up to 12 hrs
SSD	3-cell (46 WHr)	Up to 15 hrs 15 mins
SSD	3-cell (26 WHr)	Up to 9 hrs 15 mins

**Windows 7 MM07 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See www.bapco.com for additional details.

System Standby Time**

Up to 223 hrs

**Standby life will vary depending on various factors including battery, Memory, CPU, EC and LAN chip. The maximum capacity of the battery will naturally decrease with time and usage.

Power Conservation

Supports enhanced Intel SpeedStep technology (allows Battery Optimized Mode, Maximum Performance Mode, or Automatic mode) AMD PowerPlay technology (discrete models) Hibernation Standby ACPI compliance

WEIGHTS & DIMENSIONS

Weight

Non Touch Starting at 2.94 lbs/1.36 kg Weight will vary by configuration. 3-cell (26 Whr) battery, FHD, no FPR, 1 SODIMM, WLAN, lightest M.2 SSD primary storage module, no camera, no WWAN

Touch

Starting at 3.35 lbs/1.52 kg Weight will vary by configuration. 3-cell (26 Whr) battery, FHD Touch, no FPR, 1 SODIMM, WLAN, lightest M.2 SSD primary storage module, no camera, no WWAN.

Dimensions (w x d x h) Non Touch 12.2 x 8.48 x 0.83 in 31 x 21.53 x 2.1 cm Touch 12.2 x 8.48 x 0.97 in



Features

31 x 21.53 x 2.46 cm

PORTS/SLOTS

Ports

(1) DisplayPort 1.2
 (1) USB 3.0 Charging Port
 (2) USB 3.0 Port
 (1) RJ-45 / Ethernet
 (1) Side Docking connector
 (1) Headphone/Microphone Combo
 (1) AC Port
 (1) VGA Port

Expansion Slots

Media Card Reader Supports SD, SDHC, SDXC

SERVICE AND SUPPORT

HP Services offers 3-year, 1-year and 90 day limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties.* To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.

NOTE: Certain restrictions and exclusions apply. Consult the HP Customer Support Center for details. http://h20000.www2.hp.com/bizsupport/TechSupport/ProductRoot.jsp

*HP Care Packs are sold separately. Service levels and response times for HP Care Services may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. Consult the HP Customer Support Center for details. http://h20000.www2.hp.com/bizsupport/TechSupport/ProductRoot.jsp



Technical Specifications

SYSTEM UNIT

Stand-Alone Power	Nominal Operating Voltage	19.5 V	
Requirements (AC Power)	Average Operating Power	Windows 7 (64-bit)	Windows 8.1 (64-bit)
	Integrated graphics	4.75 W	4.26 W
	Max Operating Power	Discrete < 90W	
_	a	UMA < 65W	
Temperature	Operating	32° to 95° F (0° to 35° C) (not writi	
		41° to 95° F (5° to 35° C) (writing c	optical)
	Non-operating	-4° to 140° F (-20° to 60° C)	
Relative Humidity	Operating	10% to 90%, non-condensing	
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb	
	a	temperature	
Shock	Operating	40 G, 2 ms, half-sine	
.	Non-operating	200 G, 2 ms, half-sine	
Random Vibration	Operating	0.75 grms	
	Non-operating	1.50 grms	,
Altitude (unpressurized)	Operating	-50 to 10,000 ft (-15.24 to 3,048	
Diama dia darita Chandand	Non-operating 	-50 to 40,000 ft (-15.24 to 12,192 m)	
Planned Industry Standard	UL	Yes	
Certifications	CSA FCC Come l'anna	Yes	
	FCC Compliance	Yes Salast modelst	
	ENERGY STAR®	Select models*	4
	EPEAT®	Registered Gold in United States*	^
	ICES	Yes	
	Australia /	Yes	
	NZ A-Tick Compliance CCC	Vec	
		Yes	
	Japan VCCI Compliance KC	Yes Yes	
	BSMI	Yes	
	CE Marking Compliance	Yes	
	BNCI or BELUS		
	CIT	Yes Yes	
	GOST	Yes	
	Saudi Arabian Compliance	Yes	
	(ICCP)	165	
	SABS	Yes	
	UKRSERTCOMPUTER	Yes	
	UNNJENI CUPIFUI EN	165	

For accessibility information on HP products, please visit: http://www.hp.com/accessibility.



Technical Specifications

DISPLAYS

12.5" diagonal LED- backlit HD anti-glare	Outline Dimensions (W x H x D)	11.46 x 7.14 x 0.14 in (29	.1 x18.14 x 0.36 cm)
SVA flat (1366 x 768)	Active Area	10.89 x 6.12 in (27.6615	x 15.552 cm)
	Weight	0.6 lb (270g) (max)	
	Diagonal Size	12.5 in (35.75 cm)	
		200.1 (x , x)	
	Contrast Ratio	300:1 (min)	
	Refresh Rate	60 Hz	
	Brightness	200 nit (typical)	
	Pixel Resolution	Format	1366 x 768 (HD)
		Configuration	RGB Stripe
	Interface	eDP 1.2 (1 lane)	
	LCD Mode	TN	
	PPI	125 ррі	
	Viewing Angle	SVA 30/30/20/10 (min) (L SVA 45/45/35/25 (typical	
12.5" diagonal LED- Outline Dimensions 291.0mr backlit FHD Premium (W × H × D)		291.0mm x 181.4mm (ma	ax) x 2.85mm (max)
anti-glare UWVA slim Active Area		276.48mm typ. (W) x 155	.52mm typ. (H)
(1920 x 1080)	Weight	0.50 lb (230g) (max)	
	Diagonal Size	12.5 in (35.75 cm)	
	Contrast Ratio	600:1 (typ) - AG)	
	Refresh Rate	60 Hz	
	Brightness	300 nit (typical)	
	Pixel Resolution	Format Configuration	1920 x 1080 (FHD) RGB Stripe
	Interface	eDP 1.3 (2 lane)	Nud Stillhe
	LCD Mode	IPS/FFS/VA	
	PPI Viewing Angle	176 ppi	(1 - f+/D: - + + /D /11 -)
	Viewing Angle	UWVA 75/75/75/75 (min) UWVA 85/85/85/85 (typic	(Left/Right/Down/Up) cal) (Left/Right/Down/Up)



Technical Specifications

12.5" diagonal LED- backlit FHD Premium	Outline Dimensions (W × H × D)	291.0mm x 181.4mm (m	ax) x 2.85mm (max)
anti-glare UWVA slim	Active Area	276.48mm typ. (W) x 155	5.52mm typ. (H)
(1920 x 1080)+Touch	Weight	0.50 lb (230g) (max)	
	Diagonal Size	12.5 in (35.75 cm)	
	Touch enabled	Yes	
	TSP Туре	Capacitive	
Touch point supported		Min 5-point & Max 10-po	int for Win8
	Contrast Ratio	600:1 (typ) - AG)	
Refresh Rate		60 Hz	
	Brightness	300 nit (typical)	
	Pixel Resolution	Format	1920 x 1080 (FHD)
	FIXEL RESULUTION	Configuration	RGB Stripe
	Interface	eDP 1.3 (2 lane)	
	LCD Mode	IPS/FFS/VA	
PPI		176 ррі	
	Viewing Angle	UWVA 75/75/75/75 (min) UWVA 85/85/85/85 (typi) (Left/Right/Down/Up) cal) (Left/Right/Down/Up)

STORAGE AND DRIVES

320 GB* 7200 rpm SATA	Drive Weight	0.21 lbs (95 g)	
Hard Drive	Capacity	320 GB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA-8, SATA 3.0	
	Transfer Rate	Synchronous (maximum)	600 MB/s (Drive Capability)
	Seek Time	Single Track	1.5 ms-2ms
	(typical reads, including settling)	Average	12 ms-13ms
		Maximum	18ms-22 ms
	Cache	Up to 32 MB	
	Rotational Speed	7200 rpm	
	Logical Blocks	625,142,448	
	Operating Temperature	32° to 140° F (0° to 60° C)	[case temp]
	Features	ATA Security; S.M.A.R.T.IV,	, NCQ, Ultra DMA



500 GB* 7200 rpm SATA Hard Drive	Drive Weight	0.20lbs(92g- 0.21 lbs (9	15g)
	Capacity	500 GB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA-8, SATA 3.0	
	Transfer Rate	Synchronous (maximur	n) 600 MB/s (Drive Capability)
	Seek Time	Single Track	1.5 ms-2ms
	(typical reads, including	Average	12 ms-13ms
	settling)	Maximum	18ms-22 ms
	Rotational Speed	7200 rpm	
	Logical Blocks	976,773,168	
	Operating Temperature	32° to 140° F (0° to 60°	C) [case temp]
	Features	ATA Security; S.M.A.R.T.IV, NCQ, Ultra DMA	
500 GB* 7200 rpm	Drive Weight	0.21 lbs (95g)	
SMART SATA II Self Encrypting Drive	Capacity	500 GB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA-8, SATA 3.0	
	Transfer Rate	Synchronous (maximum)	300 MB/s (Drive Capability)
	Seek Time	Single Track	2 ms
	(typical reads, including settling)	Average	13 ms
	Section g,	Maximum	18 ms
	Cache	16 MB	
	Rotational Speed	7200 rpm	
	Logical Blocks	976,773,168	
	Operating Temperature	32° to 140° F (0° to 60° C) [case temp]
	Features	ATA Security; TCG OPAL v1	.00
500 GB* 5400 rpm	Drive Weight	0.21 lbs (95g)	
SMART SATA II FIPS Self Encrypting Drive	Capacity	500 GB	
Sett Encrypting Drive	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA-8, SATA 3.0	
	Transfer Rate	Synchronous (maximum)	600 MB/s (Drive Capability)
	Seek Time	Single Track	1.5 ms



	(typical reads, including settling)	- 5-	2 ms 2 ms
	Cache	16 MB	.2 1115
	Rotational Speed	5400 rpm	
	Logical Blocks	976,773,168	
	Operating Temperature	32° to 140° F (0° to 60° C) [ca	ise temp]
	Features	ATA Security; TCG Opal 2.x, F	-
		nin Security, red oput E.A., r	
1TB* 5400 rpm SATA	Drive Weight	0.21 lbs (95g)	
Hard Drive	Capacity	1 TB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA-8, SATA 3.0	
	Transfer Rate	Synchronous (maximum)	600 MB/s (Drive Capability)
	Seek Time	Single Track	2 ms
	(typical reads, including	Average	12ms-13 ms
	settling)	Maximum	18 ms-24ms
	Cache	16MB-32MB	
	Rotational Speed	5400 rpm	
	Logical Blocks	1,953,525,168	
	Operating Temperature	ture 32° to 140° F (0° to 60° C) [case temp]	
	Features	ATA Security; S.M.A.R.T.IV	, NCQ, Ultra DMA
500 GB 5400rpm + 8GI	3 Drive Weight	95g	
	¹ Capacity	500GB	
Hard Drive	Height	7mm	
	Width	70.1mm	
	Interface	ATA-8, SATA 3.0 600MB/s	
	Transfer Rate		
	Seek Time	5.6ms (Average Latency	
	(typical reads, including settling)		
	Rotational Speed	5400rpm	
	Logical Blocks	976,733,168	
	Operating Temperature	0-60 degree C	
	Features	ATA Security, S.M.A.R.T.	, NCQ, Ultra DMA



SATA 3 Gb/s 32 GB*, M.2	Drive Weight	10 Grams	
2242 Solid State Drive	Capacity	32 GB	
	Height	0.09 in (3.7 mm)	
	Width	0.87 in (22 mm)	
	Interface	ATA-8, SATA 3.0	
	Performance		Maximum Sequential Write
		Up to 380 MB/s	Up to 110 MB/s
	Logical Blocks	62,533,296	
	Operating Temperature	32° to 158°F (0° to 70°C) [ai	nbient temp]
	Features	ATA Security; DIPM; TRIM; D	•
SATA 3 Gb/s 120 GB*, M.2	Drive Weight	10 Grams	
2242 Solid State Drive	Capacity	120 GB	
	Height	0.09 in (3.7 mm)	
	Width	0.87 in (22 mm)	
	Interface	ATA-8, SATA 3.0	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 540 MB/s	Up to 480 MB/s
	Logical Blocks	234,441,648	
	Operating Temperature	32° to 158°F (0° to 70°C) [ar	nbient temp]
	Features	ATA Security; DIPM; TRIM; D	EVSLP
	Drive Weight	70 Crame	
SATA 3 Gb/s 128 GB*, 2.5- inch MLC Solid State	-	78 Grams 128 GB	
Drive	Capacity Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface		
	Performance	ATA-8, SATA 3.0 Maximum Sequential Read	Maximum Sequential Write
	Perrormance	Up to 550 MB/s	Up to 350 MB/s
	Logical Blocks	250,069,680	OP to 350 MB/S
	Operating Temperature	32° to 158°F (0° to 70°C) [ar	nhiant tamp]
	Features	ATA Security; DIPM; TRIM; D	
	reatures	ATA Security, DIPM, TRIM, D	
SATA 3 Gb/s 128 GB*, 2.5- inch TLC Solid State Drive		78 Grams	
	Capacity	128 GB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA-8, SATA 3.0	



	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 520 MB/s	Up to 140 MB/s
	Logical Blocks	250,069,680	
	Operating Temperature	32° to 158°F (0° to 70°C) [a	mbient temp]
	Features	ATA Security; DIPM; TRIM; D	-
SATA 3 Gb/s 180 GB*, 2.5-	Drive Weight	78 Grams	
inch SATA Solid State	Capacity	180 GB	
Drive	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA-8, SATA 3.0	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 540 MB/s	Up to 490 MB/s
	Logical Blocks	351,651,888	
	Operating Temperature	32° to 158°F (0° to 70°C) [a	mbient temp]
	Features	ATA Security; DIPM; TRIM; D	EVSLP
SATA 3 Gb/s 180 GB*, 2.5- inch SATA SED Solid State Drive	-	Up to 78 Grams	
	Capacity	180 GB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA-8, SATA 3.0	
	Performance	Maximum Sequential M Read	1aximum Sequential Write
		Up to 540 MB/s L	lp to 490 MB/s
	Logical Blocks	351,651,888	
	Operating Temperature	32° to 158°F (0° to 70°C) [am	•
	Features	ATA Security; DIPM; TRIM; DE	vsle; itu upat ix
SATA 3 Gb/s 240 GB*, 2.5-	Drive Weight	78 Grams	
inch Solid State Drive	Capacity	240 GB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA-8, SATA 3.0	
	Performance	Read	Iaximum Sequential Write
		Up to 540 MB/s l	Jp to 490 MB/s
	Logical Blocks	468,862,128	
	Operating Temperature	32° to 158°F (0° to 70°C) [an	ibient temp]



Technical Specifications

	Features	ATA Security; DIPM; TRIM; DEVSLP	
SATA 3 Gb/s 256 GB*, 2.5- inch Solid State Drive	-	78 Grams	
intil Joha State Brive	Capacity	256 GB	
	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface Performance	ATA8, SATA 3.0	Maximum Coquantial Write
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 520 MB/s	Up to 280 MB/s
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [a	ambient temp]
	Features	ATA Security; TCG Opal 2.>	; DIPM; TRIM; DEVSLP
SATA 3 Gb/s 256 GB*, 2.5-	Drive Weight	78 Grams	
inch Self Encrypting Solid	Capacity	256 GB	
State Drive	Height	0.28 in (7 mm)	
	Width	2.75 in (69.85 mm)	
	Interface	ATA8, SATA 3.0	
	Performance	Maximum Sequential	Maximum Sequential Write
		Read	·
		Up to 550 MB/s	Up to 500 MB/s
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [a	ambient temp]
	Features	ATA Security; TCG Opal 2.>	; DIPM; TRIM; DEVSLP
SATA 3 Gb/s 256 GB*, 2.5-	Drive Weight	10 Grams	
inch M2 PCIe Solid State	Capacity	256 GB	
Drive	Height	0.24 in (60 mm)	
	Width	0.87 in (22 mm)	
	Interface	ATA-8, PCIe 2.0	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 730 MB/s	620 MB/s
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	ATA Security; DIPM; TRIM;	DEVSLP
SATA 3 Gb/s 512 GB*, 2.5-	Drive Weight	78 Grams	
inch Solid State Drive	Capacity	32 GB	
	ταματιτή	22.00	



Technical Specifications

Width2.75 in (69.85 mm)InterfaceATA-8, SATA 3.0PerformanceMaximum Sequential ReadMaximur Dp to 550 MB/sLogical Blocks1,000,215,216Operating Temperature32° to 158°F (0° to 70°C) [ambient term	
PerformanceMaximum Sequential ReadMaximum ReadUp to 550 MB/sUp to 550Logical Blocks1,000,215,216	
Read Up to 550 MB/s Up to 550 Logical Blocks 1,000,215,216	
Logical Blocks 1,000,215,216	n Sequential Write
) MB/s
Operating Temperature 32° to 158°F (0° to 70°C) [ambient te	
	mp]
Features ATA Security; DIPM; TRIM; DEVSLP	
512 GB SATA-3 TLC Solid Drive Weight 78 Grams	
State Drive Capacity 512 GB	
Height 0.28 in (7 mm)	
Width 2.75 in (69.85 mm)	
Interface ATA-8, SATA 3.0	
Performance Maximum Sequential Read Maxi	mum Sequential Write
Up to 540 MB/sUp toLogical Blocks1,000,215,216Operating Temperature32° to 158°F (0° to 70°C) [ambient tFeaturesATA Security; DIPM; TRIM; DEVSLP	500 MB/s emp]

Networking/Communications

*For storage drives, GB = 1 billion bytes. TN = 1 trillion bytes. Actual formatted capacity is less. Upt o 16Gb (for Windows 7) and up to 30GB (for Windows 8) of system disk is reserved for system recovery software.

WIRELESS WAN (WWAN)

HP lt4112 LTE/HSPA+ Qualcomm[®] Gobi™ 4G Module *

Technology/Operating bands	g LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 800 MHz (Band 20, DD800) MHz HSPA+: 2100 (Band 1), 1900 (Band 2), 850 (Band 5), 900 (Band 8) MHz E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8) MHz
Wireless protocol standards	3GPP Release 8 LTE Specification WCDMA R99, 3GPP Release 5, 6 and 7 UMTS Specification E-GPRS: Class B, Multi-slot class 33, coding schemes CS1 - CS4 and MSC1 - MSC9
GPS GPS bands	Standalone 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz



Technical Specifications

Maximum data rates	LTE: 100 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21.6 Mbps (Download), 5.76 Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)
Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm E-GPRS 1900/1800: 26.5 dBM E-GPRS 900/850: 27.5 dBM GPRS 1900/1800: 29.5 dBm GPRS 900/850: 32.5 dBm
Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average) E-GPRS: 2,800 mA (peak); 700 mA (average)
Form Factor	M.2, 3042-S3 Key B
Weight	6 g
Dimensions (Length x Width x Thickness)	1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)

* Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

HP lt4211 LTE/EV-DO/HSPA+ Qualcomm® Gobi™ 4G Module*

Technology/Operating bands	LTE: 1900 (Band 2), 1700 (Band 4), 850 (Band 5), 700 (Band 13), 700 (Band 17), 1900 (Band 25) MHz HSPA+: 2100 (Band 1), 1900 (Band 2), 1700 (Band 4), 850 (Band 5), 800 (Band 8) MHz E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8) MHz EV-D0: 800 (BC0), 1900 (BC1) MHz
Wireless protocol standards	3GPP Release 9 LTE Specification WCDMA R99, 3GPP Release 5, 6 and 7 UMTS Specification E-GPRS: Class B, Multi-slot class 33, coding schemes CS1 - CS4 and MSC1 - MSC9 EVDO Release 0 and Release A
GPS	Standalone
GPS bands	1575.42 MHz (± 1.023 MHz), GLONASS 1596-1607MHz
Maximum data rates	LTE: 100 Mbps (Download), 50Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21.6 Mbps (Download), 5.76 Mbps (Upload) WCDMA PS: 384 kbs (Download), 384 kbs (Upload) WCDMA CS: 64 kbs (Download), 64 kbs (Upload) E-GPRS: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)
Maximum output power	LTE: 23 dBm HSPA+: 24 dBm

HSPA+: 24 dBm E-GPRS 1900/1800: 25 dBM E-GPRS 900/850: 26 dBM



Technical Specifications

	GPRS 1900/1800 : 30 dBm GPRS 900/850: 32 dBm CDMA: 24 dBM
Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average) E-GPRS: 2,800 mA (peak); 500 mA (average) EV-DO: 1000 mA (peak); 700 mA (average)
Form Factor	M.2, 3042-S3 Key B
Weight	6 g
Dimensions (Length x Width x Thickness)	1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)

* Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

HP hs3110HSPA+ Mobile Broadband Module*

Technology/Operating bands	HSPA+: 2100 (Band1), 1900 (Band 2), 1700 (Band 4), 850 (Band 5), 900 (Band 8) MHz E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 MHz (Band 5), 900 (Band 8) MHz
Wireless protocol standards	E-GPRS: Class B, Multi-slot class 33, coding schemes CS1 - CS4 and MSC1 - MSC9. UMTS/WCDMA: Release 99 and Release 7
GPS	Standalone, A-GPS
GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz
Maximum data rates	HSPA+: 21.6 Mbps (Download), 5.76 Mbps (Upload) HSPA: 7.2 Mbps (Download), 5.76 Mbps (Upload) WCDMA PS: 384 kbps (Download), 384 kbps (Upload) WCDMA CS: 64 kbps (Download), 64 kbps (Upload) E-GPRS: 296 kbps (Download), 236.8 kbps (Upload) GPRS: 107 kbps (Download), 85.6 kbps (Upload)
Maximum output power	HSPA+: 24 dBm E-GPRS 1800/1900: 26 dBm E-GPRS 850/900: 27 dBm GPRS 1800/1900: 30 dBm GPRS 850/900: 33 dBm
Maximum power consumption	2500 mA (peak); 600 mA (average)
Form Factor	M.2, 3042-S3 Key B
Weight	6 g
Dimensions (Length x Width x Thickness)	1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)

* Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors.

WIRELESS LAN (WLAN)

Intel® Dual Band Wireless-AC 7265 802.11 ac (2X2) Wi-Fi + Bluetooth®*



Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac
Interoperability Frequency Band	 Wi-Fi certified 802.11b/g/n 2.402 – 2.482 GHz Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels. 802.11a 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz Note: Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)
Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ¹	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i
	 Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI
Network Architecture Models Roaming Output Power ²	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points • 802.11b : +16dBm minimum
	• 802.11g : +14dBm minimum



	• 802.11a : +14dBm minimum		
	• 802.11n HT20(2.4GHz) : +13dBm minim	num	
	• 802.11n HT40(2.4GHz) : +13dBm minimum		
	• 802.11n HT20(5GHz) : +12dBm minimu	m	
	• 802.11n HT40(5GHz) : +12dBm minimu	m	
	• 802.11ac 80MHz(5GHz) : +11dBm minir	num	
Power Consumption	Transmit: 2.0 W (max)		
•	Receive: 1.6 W (max)		
	Idle mode (PSP): 180 mW (WLAN Associated)		
	Idle mode: 60 mW (WLAN unassociated)		
	Radio disabled: 30 mW		
Power Management	ACPI and PCI Express compliant power managen	nent	
	802.11 compliant power saving mode		
Receiver Sensitivity ³	802.11b, 1Mbps : -94dBm maximum		
	802.11b, 11Mbps : -86dBm maximum		
	802.11g, 6Mbps : -88dBm maximum		
	802.11g, 54Mbps : -74dBm maximum		
	802.11a, 6Mbps : -86dBm maximum		
	802.11a, 54Mbps : -72dBm maximum		
	802.11n, MCS07 : -69dBm maximum		
	802.11n, MCS15 : -66dBm maximum		
	802.11ac, 1SS, MCS-0 : -86dBm maximum		
	802.11ac, 1SS, MCS-9 : -61dBm maximum		
	802.11ac, 2SS, MCS-0 : -83dBm maximum		
	802.11ac, 2SS, MCS-9 : -58dBm maximum		
Antenna type	High efficiency antenna with spatial diversity, m enclosure	ounted in the display	
	Two embedded dual band 2.4/5 GHz antennas a	ro provided to the cord	
	to support WLAN MIMO communications and Blu	•	
Form Factor	PCI-Express M.2 MiniCard	etooth communications	
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm		
	Or		
	Type 1630 : 2.3 x 16.0 x 30.0 mm		
Weight	Type 2230 : 2.8g		
-	Or		
	Туре 1630 : 2g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating 14° to 158° F (–10° to	70° C)	
	Non-operating -40° to 176° F (-40° to		
Humidity	Operating 10% to 90% (non-con	-	
	Non-operating 5% to 95% (non-cond	-	
Altitude	Operating 0 to 10,000 ft (3,048 r		
	Non-operating 0 to 50,000 ft (15,240	m)	
LED Activity	LED Amber – Radio OFF; LED White – Radio ON		
1. Check latest soft	ware/driver release for updates on supported secu	rity features.	

- for updates on supported secu
- 2. Maximum output power may vary by country according to local regulations.



Technical Specifications

3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0+EDR Wireless Technology

HP Integrated Module with Blueto	oth 4.0+EDR Wireless	s Technology		
Bluetooth Specification	4.0+EDR Compliant			
Frequency Band	2402 to 2480 MHz			
Number of Available Channels	79 (1 MHz) available channels			
Data Rates and Throughput	3 Mbps data rate; th	roughput up to 2.1	7 Mbps	
	Synchronous Conne	ction Oriented links	up to 3, 64 kbps, voi	ce channels
	Asynchronous Conn	ection Less links 21	78.1 kbps/177.1 kbp	S
	asymmetric or 1306	6.9 kbps symmetric		
Transmit Power	The Bluetooth comp	onent shall operate	e as a Class II Bluetoo	th device
	with a maximum tra	nsmit power of +4	dBm for BR and EDR.	
Receiver Sensitivity	Modulation	0.01% BER	0.001% BER	
	GFSK	-80 dBm	-70 dBm	
	π/4-DQPSK	-80 dBm	-70 dBm	
	8DPSK	-80 dBm	-70 dBm	
Power Consumption	Peak (Tx) 330 mW			
	Peak (Rx) 230 mW			
	Selective Suspend 1	7 mW		
Range	Up to 33 ft (10 m)			
Electrical Interface	USB 2.0 compliant			
Bluetooth Software Supported	Microsoft Windows I	Bluetooth Software		
Link Topology				
Electrical Interface	Point to Point, Multi	point Pico Nets up t	o 7 slaves	
Bluetooth Software Supported	Full support of Blue	tooth Security Prov	isions	
Security				
Power Management	Microsoft Windows		••	
Power Management			nservation in all oper	ating
Certifications	modes, including Sta	-		
Security		• • • •	supported countries,	including:
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249			
Bluetooth Profiles Supported				
Power Management	ETS 300 328, ETS 30			
Certifications	Low Voltage Directiv			
	UL, CSA, and CE Marl			
	Serial Port Profile (S	•)	
	Service Discovery Ap	•	DAP)	
	Dial-Up Networking		12	
Certifications	Generic Object Exchange Profile (GOEP) ^{1,2} Object Push Profile (OPP) ^{1,2}			
Bluetooth Profiles Supported	File Transfer Profile			
Stactooth Fromes Supported	Synchronization Pro			
	Hard Copy Cable Rep		2	
	Personal Area Netwo			
	Human Interface De			
	FAX Profile (FAX)			
	Basic Imaging Profil	e (BIP) ²		



Technical Specifications

Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Intel® Dual Band Wireless-7265AN 802.11 a/b/g/n (2X2) Wi-Fi + Bluetooth®

Wireless LAN Standards Interoperability Frequency Band	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n Wi-Fi certified 802.11b/g/n • 2.402 – 2.482 GHz Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
	 802.11a 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz Note: Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)
Antenna Structure Data Rates	2 transmit; 2 receive (2x2) 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
Modulation Security ¹	 Direct Sequence Spread Spectrum CCK, BPSK, QPSK, 16-QAM, 64-QAM IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite



	• WAPI		
Sub-channels	Multinational support with frequency ba	nds and channels compliant to	
	local regulations.		
Network Architecture	Ad-hoc (Peer to Peer)		
Models	Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 compliant roaming between	band Access Points	
Output Power ²	• 802.11b : +16dBm minimum		
	• 802.11g : +14dBm minimum		
	 802.11a : +14dBm minimum 802.11n HT20(2.4GHz) : +13dBr 	n minimum	
	 802.11n HT40(2.4GHz) : +13dBr 802.11n HT40(2.4GHz) : +13dBr 		
	 802.11n HT20(5GHz) : +12dBm 		
	• 802.11n HT40(5GHz) : +12dBm		
Power Consumption	Transmit: 2.0 W (max)		
	Receive: 1.6 W (max)		
	Idle mode (PSP): 180 mW (WLAN Associa	-	
	Idle mode: 60 mW (WLAN unassociate Radio disabled: 30 mW	20)	
Power Management	ACPI and PCI Express compliant power m	anagomont	
rower management	802.11 compliant power saving mode	lanagement	
Receiver Sensitivity ⁴	802.11b, 1Mbps : -94dBm maximum		
	802.11b, 11Mbps : -86dBm maximum		
	802.11g, 6Mbps : -88dBm maximum		
	802.11g, 54Mbps : -74dBm maximum 802.11a, 6Mbps : -86dBm maximum 802.11a, 54Mbps : -72dBm maximum		
	802.11n, MCS07 : -69dBm maximum		
	802.11n, MCS15 : -66dBm maximum		
Antenna type	High efficiency antenna with spatial diversity, mounted in the display		
	enclosure		
	Two embedded dual band 2.4/5 GHz anto to support WLAN MIMO and Bluetooth co		
Form Factor	PCI-Express M.2 MiniCard	minumcations	
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm		
	Or		
	Type 1630 : 2.3 x 16.0 x 30.0 mm		
Weight	Type 2230 : 2.8g		
	Or		
On any time Welter an	Type 1630 : 2g		
Operating Voltage	3.3v +/- 9%	1 4° to 1 50° 5 (10° to 70° 5)	
Temperature	Operating Non-operating	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)	
Humidity	Operating	10% to 90% (non-	
mannarty	Non-operating	condensing)	
	- F	5% to 95% (non-condensing)	
Altitude	Operating	0 to 10,000 ft (3,048 m)	
	Non-operating	0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber - Radio OFF; LED White - Radi	o ON	



Technical Specifications

- 1. Check latest software/driver release for updates on supported security features.
 - 2. Maximum output power may vary by country according to local regulations.
 - 3. In Power Save Polling mode and on battery power.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CCK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
5. WLAN supplier's client utility is required for Cisco Compatible Extensions support with Microsoft Windows XP. WLAN may also be compatible with certain third-party software supplicants. WLAN supplier IHV extensions required for Cisco Compatible Extensions support for Microsoft Windows Vista.

*Wireless is an optional feature. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited.

HP Integrated Module with Bluetooth 4.0+EDR Wireless Technology

HP Integrated Module with Blueto	oth 4.0+EDR wireless	rechnology		
Bluetooth Specification	4.0+EDR Compliant	4.0+EDR Compliant		
Frequency Band	2402 to 2480 MHz			
Number of Available Channels	79 (1 MHz) available channels			
Data Rates and Throughput	3 Mbps data rate; th	roughput up to 2.1	7 Mbps	
	Synchronous Conne	ction Oriented links	up to 3, 64 kbps, voi	ce channels
	Asynchronous Conn	ection Less links 21	78.1 kbps/177.1 kbp	S
	asymmetric or 1306	.9 kbps symmetric		
Transmit Power	The Bluetooth comp	onent shall operate	e as a Class II Bluetoo	th device
	with a maximum tra	nsmit power of +4	dBm for BR and EDR.	_
Receiver Sensitivity	Modulation	0.01% BER	0.001% BER	
	GFSK	-80 dBm	-70 dBm	
	π/4-DQPSK	-80 dBm	-70 dBm	
	8DPSK	-80 dBm	-70 dBm	
Power Consumption	Peak (Tx) 330 mW			
	Peak (Rx) 230 mW			
	Selective Suspend 1	7 mW		
Range	Up to 33 ft (10 m)			
Electrical Interface	USB 2.0 compliant			
Bluetooth Software Supported	Microsoft Windows I	Bluetooth Software	!	
Link Topology				
Electrical Interface	Point to Point, Multi			
Bluetooth Software Supported	Full support of Bluetooth Security Provisions			
Security				
Power Management	Microsoft Windows ACPI, and USB Bus Support			
Power Management Certifications	Self-configurable to optimize power conservation in all operating			
	modes, including Standby, Hold, Park, and Sniff			
Security			supported countries,	including:
Certifications	FCC (47 CFR) Part 15	C, Section 15.247 8	& 15.249	
Bluetooth Profiles Supported				
Power Management	ETS 300 328, ETS 30			
Certifications	Low Voltage Directiv			
Certifications	UL, CSA, and CE Marl			
Bluetooth Profiles Supported	Serial Port Profile (SPP) ¹			
	Service Discovery Ap	oplication Profile (S	DAP)	



Technical Specifications

Dial-Up Networking (DUN)^{1,2} Generic Object Exchange Profile (GOEP)^{1,2} Object Push Profile (OPP)^{1,2} File Transfer Profile (FTP) Synchronization Profile (SYNC) Hard Copy Cable Replacement (HCRP)^{1,2} Personal Area Networking Profile (PAN)^{1,2} Human Interface Device Profile (HD)^{1,2} FAX Profile (FAX) Basic Imaging Profile (BIP)² Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Intel® 802.11 ac (2x2) WiFi + Bluetooth® 4.0 combo (Indonesia only)*

Wireless LAN Standards Interoperability Frequency Band	 IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac Wi-Fi certified 802.11b/g/n 2.402 - 2.482 GHz Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels. 802.11a 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz 5.825 - 5.850 GHz Note: Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)
Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM



Security ¹	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	Infrastructure (Access Point Required)
Roaming Output Power ²	IEEE 802.11 compliant roaming between access points 802.11b : +16dBm minimum
	• 802.11g : +14dBm minimum
	• 802.11a : +14dBm minimum
	• 802.11n HT20(2.4GHz) : +13dBm minimum
	• 802.11n HT40(2.4GHz) : +13dBm minimum
	• 802.11n HT20(5GHz) : +12dBm minimum
	• 802.11n HT40(5GHz) : +12dBm minimum
Power Consumption	 802.11ac 80MHz(5GHz) : +11dBm minimum Transmit: 2.0 W (max)
Power consumption	Receive: 1.6 W (max)
	Idle mode (PSP): 180 mW (WLAN Associated)
	Idle mode: 60 mW (WLAN unassociated) Radio disabled: 30 mW
Power Management	ACPI and PCI Express compliant power management
Receiver Sensitivity ³	802.11 compliant power saving mode 802.11b, 1Mbps : -94dBm maximum
- ,	802.11b, 11Mbps : -86dBm maximum
	802.11g, 6Mbps : -88dBm maximum 802.11g, 54Mbps : -74dBm maximum
	802.11g, 54Mbps : -74dBin maximum 802.11a, 6Mbps : -86dBm maximum
	802.11a, 54Mbps : -72dBm maximum
	802.11n, MCS07 : -69dBm maximum 802.11n, MCS15 : -66dBm maximum
	802.11ac, 1SS, MCS-0 : -86dBm maximum
	802.11ac, 1SS, MCS-9 : -61dBm maximum
	802.11ac, 2SS, MCS-0 : -83dBm maximum 802.11ac, 2SS, MCS-9 : -58dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure



Technical Specifications

	Two embedded dual band 2.4/5 GHz antennas are provided to the carc to support WLAN MIMO communications and Bluetooth communication			
Form Factor	••	PCI-Express M.2 MiniCard		
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm			
	Or			
	Туре 1630 : 2.3 x 16	.0 x 30.0 mm		
Weight	Type 2230 : 2.8g			
	Or			
	Type 1630 : 2g			
Operating Voltage	3.3v +/- 9%			
Temperature	Operating	14° to 158° F (–10° to 70° C)		
	Non-operating	–40° to 176° F (–40° to 80° C)		
Humidity	Operating	10% to 90% (non-condensing)		
	Non-operating	5% to 95% (non-condensing)		
Altitude	Operating	0 to 10,000 ft (3,048 m)		
	Non-operating	0 to 50,000 ft (15,240 m)		
LED Activity	LED Amber – Radio (DFF; LED White – Radio ON		

- 4. Check latest software/driver release for updates on supported security features.
- 5. Maximum output power may vary by country according to local regulations.
- 6. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

* Wireless is an optional feature. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. The specifications for the 802.11n WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11n WLAN devices.

HP Integrated Module with Bluetooth 4.0+EDR Wireless Technology*

Bluetooth Specification	4.0+EDR Compliant			
Frequency Band	2402 to 2480 MHz			
Number of Available Channels	79 (1 MHz) available channels			
Data Rates and Throughput	3 Mbps data rate; throughput up to 2.17 Mbps			
	Synchronous Connec	tion Oriented links	up to 3, 64 kbps, voi	ce channels
	•		78.1 kbps/177.1 kbp	S
	asymmetric or 1306	.9 kbps symmetric		
Transmit Power	-	•	e as a Class II Bluetoo	th device
	with a maximum tra	nsmit power of +4 (dBm for BR and EDR.	
Receiver Sensitivity	Modulation	0.01% BER	0.001% BER	
	GFSK	-80 dBm	-70 dBm	
	π/4-DQPSK	-80 dBm	-70 dBm	
	8DPSK	-80 dBm	-70 dBm	
Power Consumption	Peak (Tx) 330 mW			
	Peak (Rx) 230 mW			
	Selective Suspend 1	7 mW		
Range	Up to 33 ft (10 m)			
Electrical Interface	USB 2.0 compliant			
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software			
Electrical Interface	Point to Point, Multip	ooint Pico Nets up t	o 7 slaves	



Technical Specifications

Bluetooth Software Supported Security	Full support of Bluetooth Security Provisions
Power Management	Microsoft Windows ACPI, and USB Bus Support
Power Management	Self-configurable to optimize power conservation in all operating
Certifications	modes, including Standby, Hold, Park, and Sniff
Security	All necessary regulatory approvals for supported countries, including:
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Bluetooth Profiles Supported	
Power Management	ETS 300 328, ETS 300 826
Certifications	Low Voltage Directive IEC950
	UL, CSA, and CE Mark
	Serial Port Profile (SPP) ¹
	Service Discovery Application Profile (SDAP)
	Dial-Up Networking (DUN) ^{1,2}
	Generic Object Exchange Profile (GOEP) ^{1,2}
	Object Push Profile (OPP) ^{1,2}
	File Transfer Profile (FTP)
	Synchronization Profile (SYNC)
	Hard Copy Cable Replacement (HCRP) ^{1,2} Personal Area Networking Profile (PAN) ^{1,2}
Certifications	Human Interface Device Profile (HID) ^{1,2}
Bluetooth Profiles Supported	FAX Profile (FAX)
Diaetootii Fromes Supporteu	Basic Imaging Profile (BIP) ²
	Headset Profile (HSP)
	Hands Free Profile (HFP)
	Advanced Audio Distribution Profile (A2DP)

*Wireless is an optional feature. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited.

Intel® Dual Band Wireless-AC 3160 802.11 ac (1x1) Wi-Fi + Bluetooth®*

Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n
	• 2.402 – 2.482 GHz
	Note:
	The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of



	 transmitting must fully comply with requirements of 15.247 or otherwise disable those channels. 802.11a/n 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz Note: Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)
Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS7, (1SS) (20MHz, 40MHz, and 80MHz)
Modulation	Direct Sequence Spread Spectrum
Security ¹	 BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware
	 802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	• IEEE 802.11i
	 Cisco Certified Extensions, all versions through CCX4 and CCX Lite
	• WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming Output Power ²	IEEE 802.11 compliant roaming between access points • 802.11b : +16dBm minimum
	• 802.11g : +14dBm minimum
	• 802.11a : +14dBm minimum
	• 802.11n HT20(2.4GHz) : +13dBm minimum
	• 802.11n HT40(2.4GHz) : +13dBm minimum
	• 802.11n HT20(5GHz) : +12dBm minimum
	• 802.11n HT40(5GHz) : +12dBm minimum
	• 802.11ac 80MHz(5GHz) : +11dBm minimum



Technical Specifications

Power Consumption	Transmit: 2.0 W (max	()		
	Receive: 1.6 W (max)			
	Idle mode (PSP): 180 mW (WLAN Associated)			
		'LAN unassociated)		
	Radio disabled: 30 mW			
Power Management		npliant power management		
	802.11 compliant power			
Receiver Sensitivity ³	802.11b, 1Mbps : -94dB			
	802.11b, 11Mbps : -86d			
	802.11g, 6Mbps : -88dB			
	802.11g, 54Mbps : -74dl			
	802.11a, 6Mbps : -86dBi			
	802.11a, 54Mbps : -72dl			
	802.11n, MCS07 : -69dB			
	802.11n, MCS15 : -66dB			
	802.11ac, 1SS, MCS-0:-			
	802.11ac, 1SS, MCS-9: -			
		802.11ac, 2SS, MCS-0 : -83dBm maximum		
	802.11ac, 2SS, MCS-9 : -58dBm maximum High efficiency antenna with spatial diversity, mounted in the display			
Antenna type	enclosure	with spatial diversity, mounted in the display		
		d 2.4/5 GHz antennas are provided to the card		
		ommunications and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCar			
Dimensions	Type 2230 : 2.3 x 22.0 x			
	Or			
	Type 1630 : 2.3 x 16.0 x 30.0 mm			
Weight	Type 2230 : 2.8g			
	Or			
	Туре 1630 : 2g			
Operating Voltage	3.3v +/- 9%			
Temperature	Operating	14° to 158° F (–10° to 70° C)		
	Non-operating	–40° to 176° F (–40° to 80° C)		
Humidity	Operating	10% to 90% (non-condensing)		
	Non-operating	5% to 95% (non-condensing)		
Altitude	Operating	0 to 10,000 ft (3,048 m)		
	Non-operating	0 to 50,000 ft (15,240 m)		
LED Activity	LED Amber – Radio OFF;			
Check latest soft	ware/driver release for up(lates on supported security features.		

7. Check latest software/driver release for updates on supported security features.

- 8. Maximum output power may vary by country according to local regulations.
- 9. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

* Wireless is an optional feature. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. The specifications for the 802.11n WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11n WLAN devices.

HP Integrated Module with Bluetooth 4.0+EDR Wireless TechnologyBluetooth Specification4.0+EDR Compliant

Bluetooth Specification	4.0+EDR Compliant
Frequency Band	2402 to 2480 MHz

Number of Available Channels	70 (1 MHz) available	channels		
Data Rates and Throughput	79 (1 MHz) available channels 3 Mbps data rate; throughput up to 2.17 Mbps			
Data Kates and Throughput	Synchronous Connec	• • •	•	ico channols
	Asynchronous Conne			
	asymmetric or 1306		/o.1 kuµs/1//.1 ku	72
Transmit Power	The Bluetooth comp		a ac a Class II Blueto	ath device
Transmitt ower		•		
Receiver Sensitivity	with a maximum transmit power of +4 dBm for BR and EDR. Modulation 0.01% BER 0.001% BER			ר ר
	GFSK	-80 dBm	-70 dBm	-
	π/4-DQPSK	-80 dBm	-70 dBm	
	8DPSK	-80 dBm	-70 dBm	
Power Consumption	Peak (Tx) 330 mW			_
-	Peak (Rx) 230 mW			
	Selective Suspend 1	7 mW		
Range	Up to 33 ft (10 m)			
Electrical Interface	USB 2.0 compliant			
Bluetooth Software Supported	Microsoft Windows B	Bluetooth Software		
Link Topology				
Electrical Interface	Point to Point, Multi			
Bluetooth Software Supported Security	Full support of Bluetooth Security Provisions			
Power Management	Microsoft Windows ACPI, and USB Bus Support			
Power Management	Self-configurable to optimize power conservation in all operating			
Certifications	modes, including Standby, Hold, Park, and Sniff All necessary regulatory approvals for supported countries, including:			
Security				, including:
Certifications	FCC (47 CFR) Part 15	C, Section 15.247 8	k 15.249	
Bluetooth Profiles Supported				
Power Management	ETS 300 328, ETS 30			
Certifications	Low Voltage Directiv			
	UL, CSA, and CE Mark Serial Port Profile (SPP) ¹			
	Service Discovery Application Profile (SDAP)			
	Service Discovery Application Profile (SDAP) Dial-Up Networking (DUN) ^{1,2}			
	Generic Object Excha		1,2	
	Object Push Profile (
	File Transfer Profile	(FTP)		
Certifications	Synchronization Pro			
Bluetooth Profiles Supported	Hard Copy Cable Rep			
Blactoblin i brites Supported	Personal Area Netwo Human Interface Dev		1,2	
	FAX Profile (FAX)			
	Basic Imaging Profile	e (BIP) ²		
	Headset Profile (HSF			
	Hands Free Profile (I			
	Advanced Audio Dist	ribution Profile (A2	DP)	



Technical Specifications

AUDIO/MULTIMEDIA - DTS STUDIO SOUND™

Hardware	Implementation	ALC3228
	Function Key Volume Controls	Volume up, volume down, and mute
	Full Duplex	Yes
	Microphone In	Stereo
	Headphone/Line Out	Stereo
	Integrated Microphone	Yes, dual digital microphone array
Audio Output Quality	Frequency Response	20 Hz – 20 kHz
	Signal to Noise Ratio	>85 dB
	Total Harmonic Distortion	0.01%
	Noise Floor	–110 dB
	Play/Record Sampling Rate(s)	8 kHz – 48kHz
	DAC	16, 20 or 24-bit
	ADC	16 or 20-bit
Integrated Stereo	Power Rating	2 Watts
Speakers	Impedance	4 Ohms

SECURITY

HP Fingerprint Reader	Mobile Voltage Operation	1 3.0V-3.6V
(optional)	Operating Temperature	14° – 167°F (-10° – 75°C)
	Current Consumption Image	36 mA peak
	Low Latency Wait for Finger	950 uA
	Capture Rate	6000 lines/sec
	ESD Resistance	IEC 61000-4-2 4B (±15KV)
	Detection Matrix	200*1 (plus another secondary line) 508 dpi 12*3 mm sensor area
Smart Card Reader	Smart card standard	PC/SC 2.0 for Windows smart card standard
	Dimensions (L x W x H)	0.41x 0.08 x 0.32 in (10.5 x 2 x 8.2 mm)
	Smart Card support	ISO 7816 Class A and AB smart cards
	Smart Card Interface	Smart Card Interface with T = 0 and T = 1 support Support I2C memory card, SLE4418, SLE4428, SLE4432, SLE4442, SLE4436, SLE5536, SLE6636, AT88SC1608, AT45D041 card and AT45DB041 card via external EEPROM



Technical Specifications

Ор	erating systems	No driver is required for this device. Native support is provided by the		
Po			With card present, before being suspended: 40.9 mA Without card present, before being suspended: 33.16 mA After being suspended with smart card present: 380 µA After being suspended without smart card present: 380 µA	
		Power Saving Mode	With card present, before being suspended: 40.6 mA Without card present: 380 μA After being suspended with smart card present: 380 μA	
Power	atures	SLE4436, SLE5536, SLE card via exter Support ISO78 Implemented endpoint, Mas Storage endp Built-in PLL fo Support EEPR iManufacturer accessing mer EEPROM prog Support softw Support softw Support short Compatible w Support remo Support USB s Support Power Normal/PWR s Built in resona	I protocol emory card, SLE4418, SLE4428, SLE4432, SLE4442, 5636, AT88SC1608, AT45D041 card and AT45DB041 hal EEPROM 816 Class A, B and C (5V/3V/1.8V) card as an USB full speed device with bulk transfer s bint r USB and Smart Card clocks requirement OM for USB descriptors customization (PID/VID/ /iProduct/Serial Number), Direct Web Page Link, and nory card module. rammable via USB interface are update for memory card module t Web Page Link via configuration in external EEPROM APDU and extended APDU th Microsoft USB-CCID driver te wake up through inserting card/removing card elective suspend r Saving Mode (Using one pin to select between Saving Mode) oower over current protection mechanism itor.	
HP 45W Smart AC Adapter Non-Slim & Non-Slim 2	r Dimensions Input	95.0 x 40.0 x 26.5m 90 to 265 VAC	m	
Prong	-	Input Efficiency Input frequency rai Input AC current	88% min at 115 VAC / 89% min at 230VAC 19e 47 to 63 Hz 1.4 A at 90 VAC and maximum load	



POWER

Output	Output power	45W
	DC output	19.5V
	Hold-up time	5 msec at 115 VAC input
	Output current limit	<8A, Over voltage protection- 29V max automatic shutdown
Connector	3 pin/grounded, mates wit	th interchangeable cords
Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
	Non-operating (storage) temperature	-4° to 121° F (-20° to 85° C)
	Altitude	0 to 16,405 ft (0 to 5,000 m)
	Humidity	0% to 95%
	Storage Humidity	0% to 95%
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives; Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B CCC, NOM-1 NYCE; Reliability - failure rate of less than 0.1% annually within the first three years of operation.	

HP 65W EM AC Adapter	Dimensions	4.98 x 1.97 x 1.18 in (12.65 x 5.0 x 3.0 cm)		
(China and India only)	Weight	0.62 lb (300 g) max		
	Input	90 to 265 VAC		
		Input Efficiency	87% min at 115 VAC/230VAC	
		Input frequency range	47 to 63 Hz	
		Input AC current	1.7 A at 90 VAC	
	Output	Output power	65W	
		DC output	19.5V	
		Hold-up time	5 msec at 115 VAC input	
		Output current limit	<11A, Over voltage protection- 29V max automatic shutdown	
	Connector	3 pin/grounded, mates with 4.5mm barrel type Smart ID DC connector		
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)	
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)	
		Altitude	0 to 16,405 ft (0 to 5,000 m)	
		Humidity	20% to 95%	
		Storage Humidity	10% to 95%	
	EMI and Safety	CE Mark - full compliance	with LVD and EMC directives; Worldwide safety	



Technical Specifications

	Certifications	- C-UL-US, NORDICS, DENA	60950, UL60950, Class1, SELV; Agency approvals AN, EN55022 Class B, FCC Class B, CISPR22 Class B, over 200,000 hours at 25°C ambient condition.	
3-cell HP Long Life	Dimensions (H × W × L)	0.85 x 1.76 x 10.59 in (2.1	16 x 4.46 x 26.9 cm)	
(26WHr) Lithium-Ion	Weight	168.5 g		
Polymer	Cells/Type	3-cell Lithium-Ion Polymer		
	Energy	Voltage	11.1	
		Amp-hour capacity	4.4Ah	
		Watt-hour capacity	26.3Wh	
	Temperature	Operating (Charging)	32° to 113° F (0° to 45° C)	
		Operating (Discharging)	14° to 122° F(-10° to 50° C)	
		Non-operating	-4° to 122° F (-20° to 50° C)	
	Battery Re-Charge Time	System in OFF or Standby Mode	2.5 hours	
	Fuel Gauge LED	No		
	Warranty	1 year or 3 years* *Battery warranty depend	ds on the platform warranty.	
	Optional Travel Battery Available	No		
3-cell HP Long Life (46WHr) Lithium-Ion	Dimensions (H x W x L) Weight	7.47x3.85x0.51in (18.97) 255 g	x9.78x1.29cm)	
Polymer	Cells/Type	3-cell Lithium-Ion Polyme	er	
	Energy	Voltage	11.1	
		Amp-hour capacity	4.15Ah	
		Watt-hour capacity	46Wh	
	Temperature	Operating (Charging)	32° to 113° F (0° to 45° C)	
	· •	Operating (Discharging)	14° to 140° F(-10° to 60° C)	
		Non-operating	-4° to 140° F (-20° to 60° C)	
	Battery	System in OFF or	3 hours	
	Re-Charge Time	Standby Mode		
	Fuel Gauge LED	No		
	Warranty	1 year or 3 years* *Battery warranty depend	ds on the platform warranty.	
	Optional Travel Battery Available	No		

ENVIRONMENTAL



Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® EPEAT <goid> registered in the United States. See http://www.epeat.net for registration status in your country. The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".</goid>		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	9.28 W	9.92 W	9.88 W
Normal Operation (Long idle)	4.43 W	4.35 W	6.64 W
Sleep	0.63 W	0.66 W	0.63 W
Off	0.26 W	0.28 W	0.26 W
	Note: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental		



	Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.		
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	32 BTU/hr	34 BTU/hr	34 BTU/hr
Normal Operation (Long idle)	15 BTU/hr	15 BTU/hr	23 BTU/hr
Sleep	2 BTU/hr	2 BTU/hr	2 BTU/hr
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr
	*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.		
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (LWAd, bels)	Sound Pressure (LpAm, decibels)	
Typically Configured – Idle	2.9	24	
Fixed Disk – Random writes	3.1	26	
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC		
	Batteries used in the product do not contain: Mercury greater the1ppm by weight		



HP EliteBook 820 G2 Notebook PC

QuickSpecs

Cadmium greater than 20ppm by weight
Battery size: CR2320 (coin cell) Battery type: Lithium Battery size: 6-cell high capacity Lithium- Ion battery (optional 8 cell available) Battery type:
 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT)



	•	standard at the < gold> level, see www.epeat.n et Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. This product contains 0% post- consumer recycled plastic (by wt.) This product is 96.6% recycle-able when properly disposed of at end of life.		
Packaging Materials	1.	External:	PAPER/Corru gated	372 g
	2.	Internal:	PLASTIC/EPE (Expanded Polyethylene)	43.7 g
	3.		PLASTIC/Poly ethylene low density	26 g
	4.	The plastic packaging material contains at least 50% recycled content.		
	5.	The corrugated paper packaging materials contains at		



Technical Specifications

least 70% recycled content.

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hp info/globalcitizenship/ environment/pdf/gse. pdf):

- Asbestos
- Certain Azo
 Colorants
- Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
- Cadmium
- Chlorinated
 Hydrocarbons
- Chlorinated
 Paraffins
- Formaldehyd e
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external



Technical Specifications

- surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominat ed Biphenyls (PBBs)
- Polybrominat ed Biphenyl Ethers (PBBEs)
- Polybrominat ed Biphenyl Oxides (PBBOs)
- Polychlorinat ed Biphenyl (PCB)
- Polychlorinat ed Terphenyls (PCT)
- Polyvinyl Chloride (PVC)

 except for wires and cables, and certain retail packaging has been voluntarily removed from most
 - applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

6.

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product



Technical Specifications

packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozonedepleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of postconsumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportatio n fuel
- efficiency.
 Plastic packaging materials are marked according to ISO 11469



Technical Specifications

	and DIN 6120
	standards.
End-of-life Management and Recycling	Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go /reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go /recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
Hewlett-Packard Corporate Environmental Information	For more information about HP's commitment to the environment:
	Global Citizenship Report

http://www.hp.com/hp

Technical Specifications

info/globalcitizenship/ gcreport/index.html Eco-label certifications http://www8.hp.com/ us/en/hpinformation/environm ent/ecolabels.html ISO 14001 certificates: http://www.hp.com/hp info/globalcitizenship/ environment/pdf/PC_G BU_ Product_Design_ISO_1 4K_Certificate.pdf and http://www.hp.com/hp info/globalcitizenship/ environment/pdf/cert. pdf

COUNTRY OF ORIGIN

China



Summary of Changes

Туре	Description	Part #
Cases	HP Slim Ultrabook Messenger (up to 15.6" x .88"/22/5mm)	F3W14AA
	HP Slim Ultrabook Top Load (up to 15.6" x .88"/22/5mm)	F3W15AA
	HP Slim Ultrabook Backpack (up to 15.6" x .88"/22/5mm)	F3W16AA
	HP Ultrabook Sleeve (up to 14.0/35.6cm x 1"/25.4mm)	F7Z99AA
	HP Ultrabook Sleeve (up to 15.6"/39.8cm x 1"/25.4mm)	F8A00AA
Docking	HP UltraSlim Docking Station	D9Y32AA#xxx
	HP USB 3.0 Port Replicator	H1L08AA#xxx
	Universal Port Replicator	E6D70AA#xxx
Input/Output – Mice	HP USB Travel Mouse	G1K28AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP Ultra Mobile Wireless Mouse	H6F25AA#xxx
Input/Output – Keyboards	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP Slim BT Keyboard	H4Q44AA#xxx
Input/Output – Adapters	HP DP to HDMI 1.4 Adapter	F3W43AA
	HP DisplayPort to DVI Adapter	F7W96AA
	HP Wireless Display Adapter	J1V25AA#xxx
_	HP Dual Output USB Graphics Adaptor	C5U89AA
Power	HP 65W Slim AC Adapter	H6Y82AA#xxx
	HP 90W Slim AC Adapter	H6Y83AA#xxx
	HP 90W Slim Combo AC Adapter w/ USB	H6Y84AA#xxx
	HP 45W Smart AC Adapter	H6Y88AA#xxx
	HP 65W Smart AC Adapter	H6Y89AA#xxx
0 - the state	HP 90W Smart AC Adapter	H6Y90AA#xxx
Batteries	HP SB03XL Notebook Battery	E7U25AA
Security	HP UltraSlim Keyed Cable Lock	
	HP Docking Station Cable Lock	AU656AA#XXX
Storage - External Storage	HP 12.5 NB Privacy Filter HP USB External DVDRW Drive	J6E64AA
Displays		F2B56AA
σιοριαγο	HP EliteDisplay S231d 23-in IPS LED BLU Notebook Docking Monitor	FOW81AA
	HP EliteDisplay S240ml 23.8-in IPS LED Backlit MHL Monitor	FUWOTAA F4M47AA
	HP EliteDisplay 524011 23.8-11 IPS LED Backlit Mint Monitor	F4M47AA F0W81AA
		10000188



Summary of Changes

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Summary of Changes

Date of change:	Version History:		Description of change:
January 20, 2015	Version 1 to 2	Added	The words 'up to' to all battery life specs
January 26, 2015	V2 to V3	Added	Environmental information and stand by time
March 18, 2015	V3 to V4	Changed	Memory unit speed spec on page 8
April 10, 2015	V4 to V5	Removed	Surface Treatment Anti Glare page 16 and 17
June 29, 2015	V5 to v6	Added	Windows 10 to overview on page 4, OS list on page5 and footnotes to pages 5 & 7
		Updated	TPM Embedded Security Chip to 1.2
		Removed	2013 from name of HP UltraSlim Docking Station
November 19, 2015	V6 to v7	Added	VGA Port page 7
December 4, 2015	V7 to v8	Changed	12.5" diagonal LED-backlit FHD Premium anti-glare UWVA slim (1920 x 1080)+Touch
January 20, 2016	V8 t0 V9	Added	BIOS adheres to NIST SP800-147 to footnote 2 on Software BIOS section
May 27, 2016	V9 to v10	Removed Added	HP 2.4 GHz Keyboard and Mouse G1K29AA HP Slim Wireless Keyboard and Mouse T6L04AA

